

Feature

- The chips are electrically insulated from bottom plate, 2500V AC voltage
- Complete pressure connection structure, with excellent temperature Characteristics and power cycling capacity
- Forced air cooling for modules below 400A and air cooling or water Cooling for modules above 500A

Typical application

- DC power supplies of appliances and devices
- AC and DC motor control, Soft starting for motors
- Various rectifying power supply
- Electric welders, Frequency transformers, Battery charging and discharging

I _{F(AV)}	800A
V _{RRM}	500-2500V
I _{FSM}	18 KA
I ² t	1650 10 ³ a ² s

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _J (°C)	VALUE		UNIT
				Min	Max	
I _{F(AV)}	Mean forward current	180° half sine wave, 50HZ Single heat sink, T _C =98°C	150		800	A
I _{T(RMS)}	RMS current		150		1256	A
V _{RRM}	Repetitive peak reverse voltage	V _{DRM} &V _{RRM} tp=10ms V _{DSM} &V _{RSM} =V _{DRM} &V _{RRM} +200V	150	500	2500	V
I _{RRM}	Repetitive peak current	V _{RM} =0V _{RRM}	150		40	mA
I _{FSM}	Surge on-state current	10ms half sine wave V _R =0.6V _{RRM}	150		18.0	KA
I ² t	I ² t for fusing coordination				1650	A ^{2S*10}
V _{TO}	Threshold voltage		150		0.75	V
r _T	On-state slop resistance				0.34	mΩ
V _{FM}	Peak on-state voltage	I _{TM} =80A	25		1.40	V
R _{th(j-c)}	Thermal impedance node to the shell	180 ° sine wave, single heat sink			1.72	°C/W
R _{th(e-h)}	Thermal impedance (shell to powder)	180 ° sine wave, single heat sink			0.080	°C/W
V _{iso}	Insulation voltage			2500		V
F _M	Mounting force (M5)				16	N-m
	Mounting force (M6)				6	N-m
T _{stq}	Stored temperature			-40	125	°C
W _t	Weight					g
Outline						

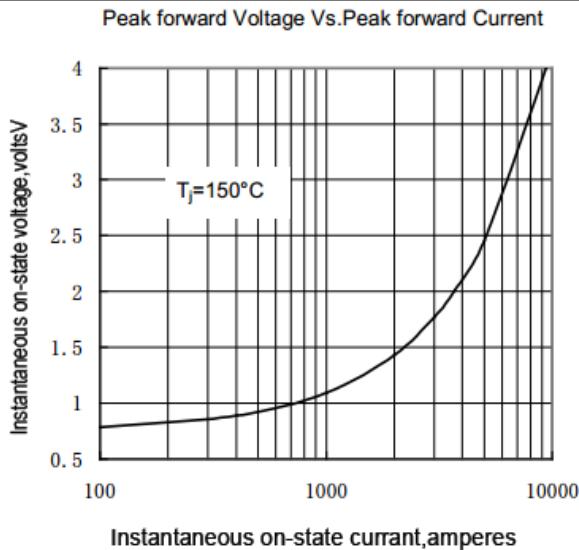


Fig.1

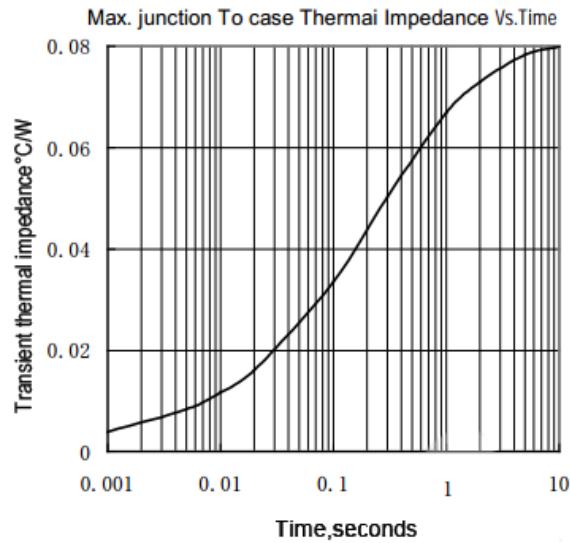


Fig.2

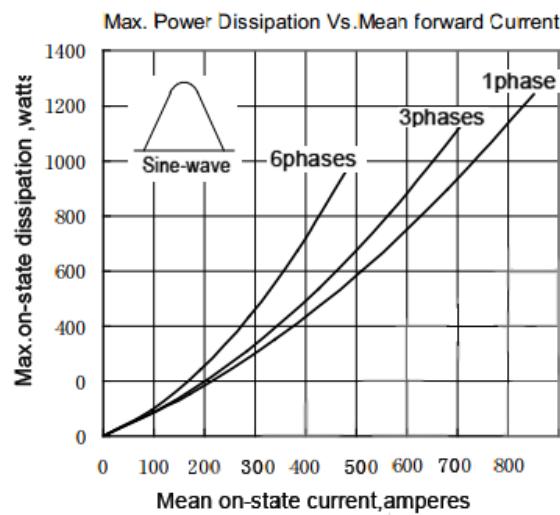


Fig.3

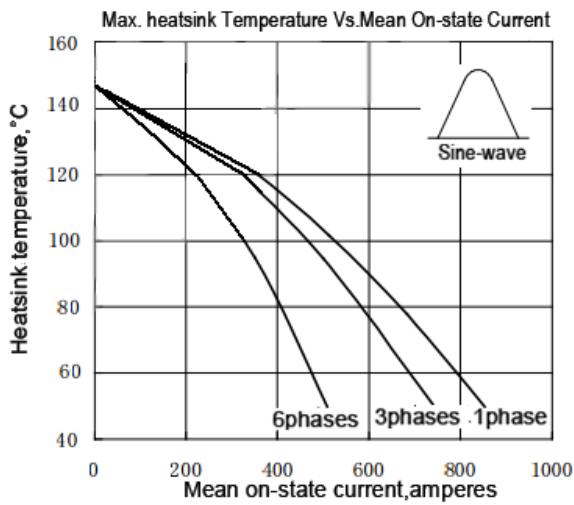


Fig.4

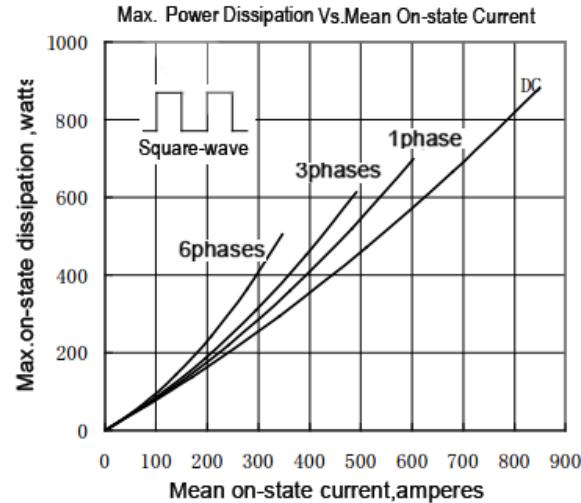


Fig.5

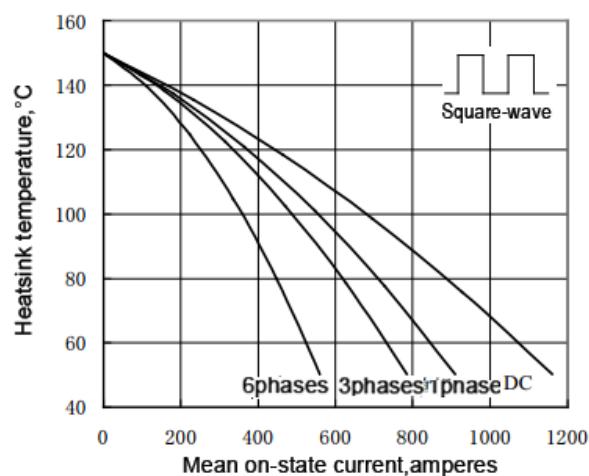


Fig.6

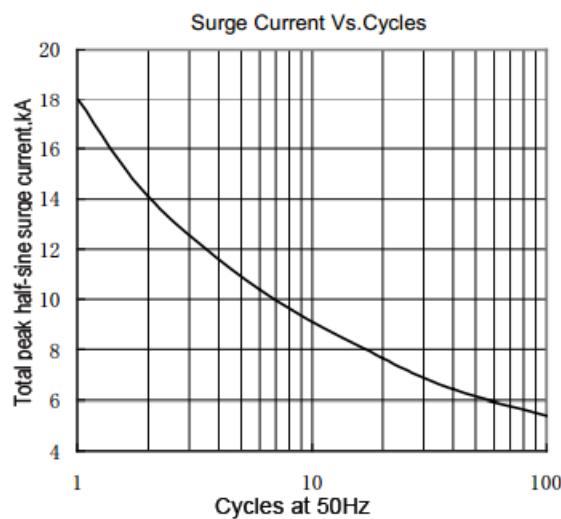


Fig.7

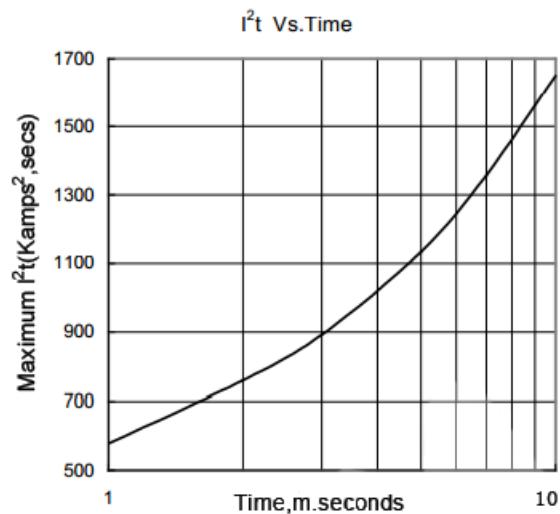
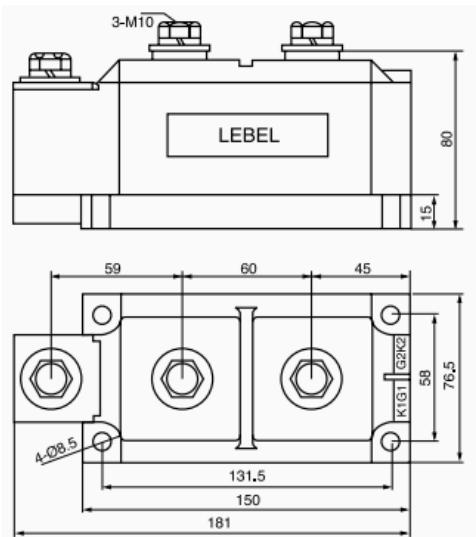
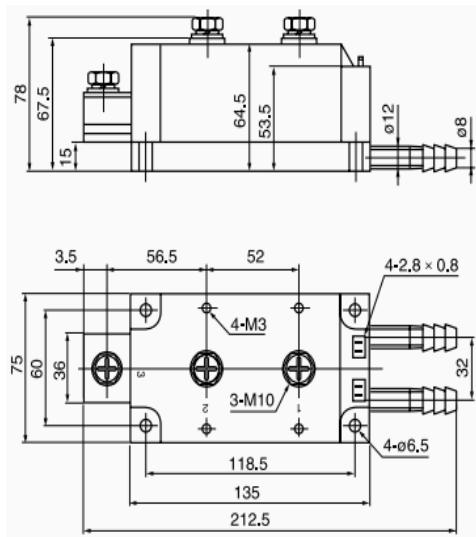


Fig.8

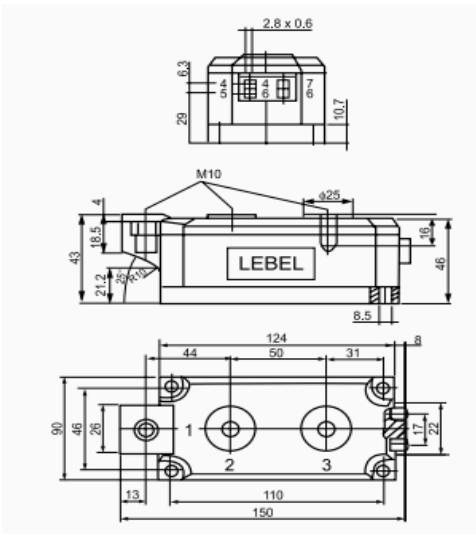
Outline:



1



2



3

Circuit Drawing: